

TN4612LNSG

N-Channel Enhancement Mode Power MOSFET

Product Summary

- V_{DS}= 20V,I_D= 6.5A
- $R_{DS(on)}=20m\Omega @V_{GS}=4.5V$
- $R_{DS(on)}=25m\Omega @V_{GS}=2.5V$

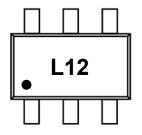
Features

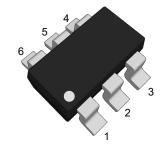
- Advanced Trench Technology
- RoHS and Reach Compliant
- Halogen and Antimony Free
- Moisture Sensitivity Level 3

Application

- Load Switch
- PWM Applications
- Power Management

Marking Code



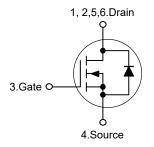


SOT-23-6

(Top View)

Pin	Description	
1,2,5,6	Drain	
3	Gate	
4	Source	

Schematic Diagram



Absolute Maximum Ratings

Ratings at 25°C ambient temperature unless otherwise specified.

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	20	V
V _{GS}	Gate-Source Voltage	±12	V
ID@T _A =25°C	Continuous Drain Current, V _{GS} @ 4.5V ¹	6.2	Α
ID@TA=100°C	Continuous Drain Current, V _{GS} @ 4.5V ¹	4	Α
I _{DM}	Pulsed Drain Current ²	22.5	А
P _D @T _A =25°C	Total Power Dissipation ³	1.0	W
T _{STG}	Storage Temperature Range -55 to 150 °C		°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
Reja	Thermal Resistance Junction-ambient ¹		48	°C/W
Rejc	Thermal Resistance Junction-Case ¹			°C/W

Electrical Characteristics

(Ta=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Charac	cteristic					
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250µA	20	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V,	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±12V	-	-	±100	nA
On Charac	cteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_{D}=25$	0.4	0.7	1	V
	Static Drain-Source on-Resistance	V _{GS} =4.5V, I _D =4A	-	19	24	mΩ
$R_{DS(on)}$	note2	V _{GS} =2.5V, I _D =3A	-	25	41	
Dynamic (Characteristics					
C _{iss}	Input Capacitance		-	328	-	pF
Coss	Output Capacitance	V _{DS} =10V, V _{GS} =0V,	-	69.3	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	58.5	-	pF
Qg	Total Gate Charge	\/ -40\/ I -0A	-	5.6	-	nC
Q _{gs}	Gate-Source Charge	V_{DS} =10V, I_{D} =2A, V_{GS} =4.5V	-	0.8	-	nC
Q_{gd}	Gate-Drain("Miller") Charge	─ V _{GS} -4.5V	-	1	-	nC
Switching	Characteristics					
t _{d(on)}	Turn-on Delay Time)/ 40)/	-	5	-	ns
t _r	Turn-on Rise Time	V _{DS} =10V,	-	30	-	ns
t _{d(off)}	Turn-off Delay Time	$I_D=4A$, $R_{GEN}=3\Omega$,	-	48	-	ns
t _f	Turn-off Fall Time	V _{GS} =4.5V	-	36	-	ns
Drain-Sou	rce Diode Characteristics and Maxim	um Ratings	•			
Is	Maximum Continuous Drain to Source Diode Forward Current		-	-	6.2	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	22.5	А
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =4A	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

^{2.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%

Typical Characteristic Curves

Figure1: Output Characteristics

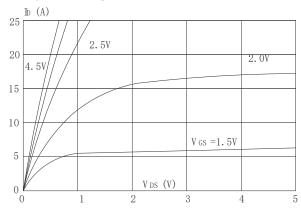


Figure 2:Typical Transfer Characteristics

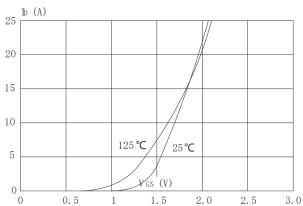


Figure 3.On-resistance vsDrain Current

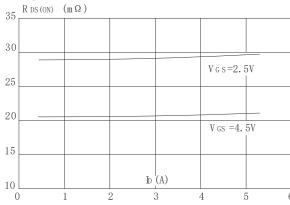


Figure 4: Body Diode Characteristics & (A)

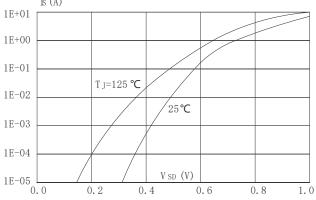


Figure 5: Gate Charge Characteristics

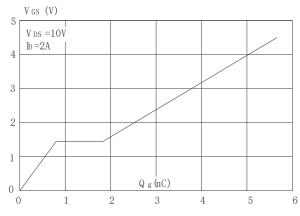


Figure 6: Capacitance Characteristics

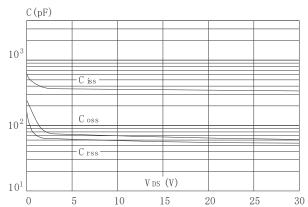


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

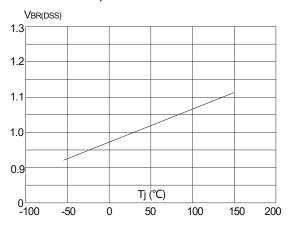


Figure 9: Maximum Safe Operating Area

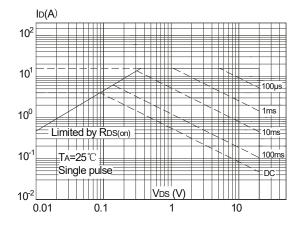


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

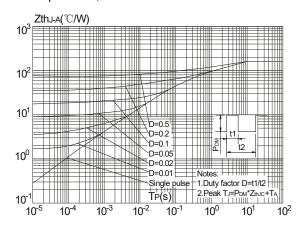


Figure 8: Normalized on Resistance vs. Junction Temperature

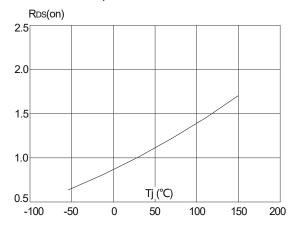
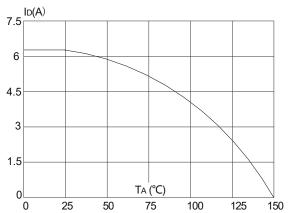


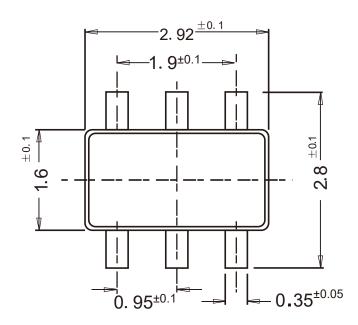
Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

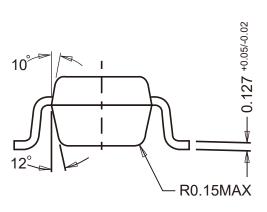


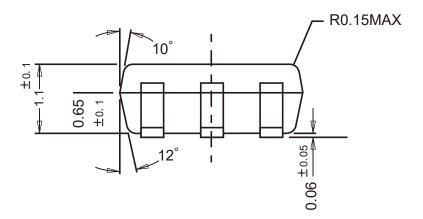
Package Outline

SOT-23-6

Dimensions in mm





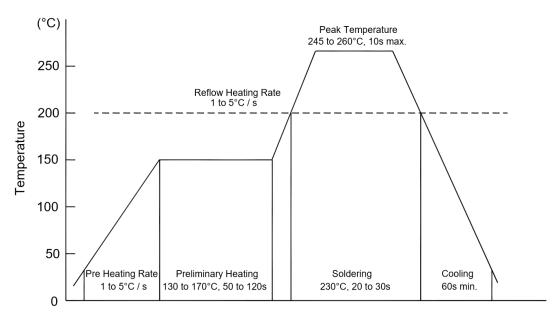


Ordering Information

Device	Package	Shipping
TN4612LNSG	SOT-23-6	3,000PCS/Reel&7inches

Conditions of Soldering and Storage

Recommended condition of reflow soldering



Recommended peak temperature is over 245 °C. If peak temperature is below 245 °C, you may adjust the following parameters:

- Time length of peak temperature (longer)
- Time length of soldering (longer)
- Thickness of solder paste (thicker)

Conditions of hand soldering

Temperature: 370 °C

Time: 3s max.Times: one time

Storage conditions

Temperature

5 to 40 °C

Humidity

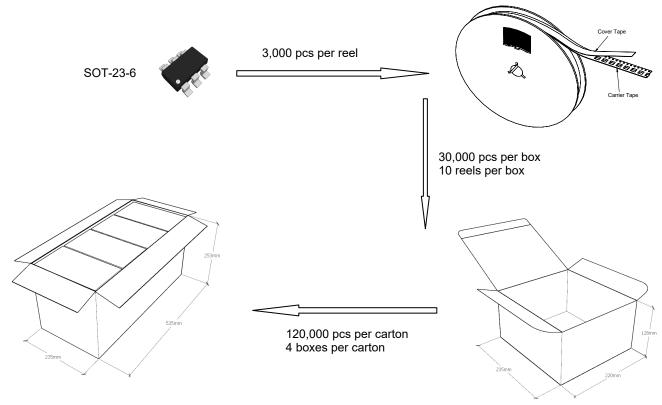
30 to 80% RH

Recommended period

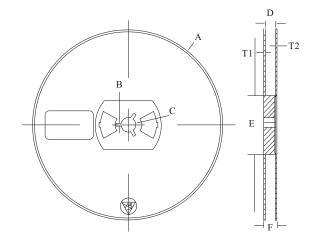
One year after manufacturing

Package Specifications

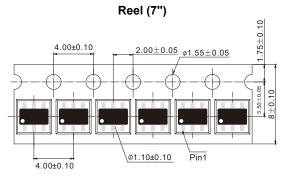
• The method of packaging



♦ Embossed tape and reel data



Symbol	Value (unit: mm)	
Α	Ø 177.8±1	
В	2.7±0.2	
С	Ø 13.5±0.2	
E	Ø 54.5±0.2	
F	12.3±0.3	
D	9.6+2/-0.3	
T1	1.0±0.2	
T2	1.2±0.2	



Tape (8mm)

Contact Information

TANI website: http://www.tanisemi.com Email:tani@tanisemi.com

For additional information, please contact your local Sales Representative.



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Product Specification Statement

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The product parameters described in the product specification are numerical values, characteristics, and functions obtained through actual testing or theoretical calculations of the product in an independent or ideal state. Due to the complexity of product applications and variations in test conditions and equipment, there may be slight fluctuations in parameter test values. TANI shall not guarantee that the actual performance of the product when installed in the customer's system or equipment will be entirely consistent with the product specification, especially concerning dynamic parameters. It is recommended that users consult with professionals for product selection and system design. Users should also thoroughly validate and assess whether the actual parameters and performance when installed in their respective systems or equipment meet their requirements or expectations. Additionally, users should exercise caution in verifying product compatibility issues, and TANI assumes no responsibility for the application of the product. TANI strives to provide accurate and up-to-date information to the best of our ability. However, due to technical, human, or other reasons, TANI cannot guarantee that the information provided in the product specification is entirely accurate and error-free. TANI shall not be held responsible for any losses or damages resulting from the use or reliance on any information in these product specifications.

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Users are advised to pay attention to the parameter limit values specified in the product specification and maintain a certain margin in design or application to ensure that the product does not exceed the parameter limit values defined in the product specification. This precaution should be taken to avoid exceeding one or more of the limit values, which may result in permanent irreversible damage to the product, ultimately affecting the quality and reliability of the system or equipment.

The design of the product is intended to meet civilian needs and is not guaranteed for use in harsh environments or precision equipment. It is not recommended for use in systems or equipment such as medical devices, aircraft, nuclear power, and similar systems, where failures in these systems or equipment could reasonably be expected to result in personal injury. TANI shall assume no responsibility for any consequences resulting from such usage.

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